

Abstract

A circuit board having stable connection resistance can be obtained. The multi-layer circuit board includes the steps of making through-holes in an incompressible substrate having films on either side thereof via a bonding layer; filling conductive paste into the through-holes; removing the films from the substrate; laminating metallic foils to either side of the substrate and heating same under pressures to harden the bonding layer, bonding the metallic foils to the substrate and electrically connecting the sides of the substrate to each other; and forming a circuit pattern by machining the metallic foils.